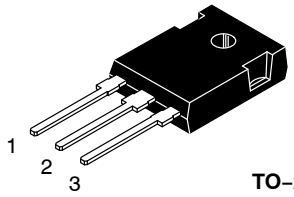
NPN Silicon Power Transistors High Voltage Planar

MJW18020

30 AMPERES
1000 VOLTS BV_{CES}
450 VOLTS BV_{CEO}, 250 WATTS

The MJW18020 planar High Voltage Power Transistor is specifically Designed for motor control applications, high power supplies and UPS's for which the high reproducibility of DC and Switching parameters minimizes the dead time in bridge configurations.

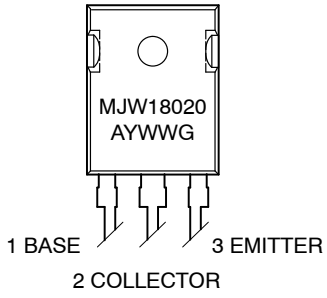


TO−247
CASE 340L

Features

- High and Excellent Gain Linearity
- Fast and Very Tight Switching Times Parameters t_{si} and t_{fi}
- Very Stable Leakage Current due to the Planar Structure
- High Reliability
- Pb−Free Package is Available*

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector−Emitter Sustaining Voltage	V_{CEO}	450	Vdc
Collector−Emitter Breakdown Voltage	V_{CES}	1000	Vdc
Collector−Base Voltage	V_{CBO}	1000	Vdc
Emitter−Base Voltage	V_{EBO}	9.0	Vdc
Collector Current − Continuous − Peak (Note 1)	I_C	30 45	Adc
Base Current − Continuous − Peak (Note 1)	I_B	6.0 10	Adc
Total Power Dissipation @ T_C = 25°C Derate Above 25°C	P_D	250 2.0	W W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	0.5	°C/W
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	50	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	T_L	275	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Pulse Test: Pulse Width = 5 μs, Duty Cycle ≤ 10%.

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ORDERING INFORMATION

Device	Package	Shipping
MJW18020	TO−247	30 Units/Rail
MJW18020G	TO−247 (Pb−Free)	30 Units/Rail

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector−Emitter Sustaining Voltage (I_C = 100 mAdc, I_B = 0)		$V_{CEO(sus)}$	450	–	–	Vdc
Collector Cutoff Current (V_{CE} = Rated V_{CEO}, I_B = 0)		I_{CEO}	–	–	100	μAdc
Collector Cutoff Current (V_{CE} = Rated V_{CES}, V_{EB} = 0)		I_{CES}	–	–	100	μAdc
(T_C = 125°C)					500	
Emitter Cutoff Current (V_{CE} = 9 Vdc, I_C = 0)		I_{EBO}	–	–	100	μAdc
ON CHARACTERISTICS						
DC Current Gain	(I_C = 3 Adc, V_{CE} = 5 Vdc)	h_{FE}	14		34	
	(T_C = 125°C)		–	30	–	
	(I_C = 10 Adc V_{CE} = 2 Vdc)		8	16		
	(T_C = 125°C)		5	14	–	
	(I_C = 20 Adc V_{CE} = 2 Vdc)		5.5	9	–	
	(T_C = 125°C)		4	7	–	
	(I_C = 10 mAdc V_{CE} = 5 Vdc)		14	25	–	
Base−Emitter Saturation Voltage	(I_C = 10 Adc, I_B = 2 Adc)	$V_{BE(sat)}$	–	0.97	1.25	Vdc
	(I_C = 20 Adc, I_B = 4 Adc)			1.15	1.5	
Collector−Emitter Saturation Voltage		$V_{CE(sat)}$				Vdc
(I_C = 10 Adc, I_B = 2 Adc)			–	0.2	0.6	
	(T_C = 125°C)		–	0.3	–	
(I_C = 20 Adc, I_B = 4 Adc)			–	0.5	1.5	
	(T_C = 125°C)		–	0.9	2.0	
DYNAMIC CHARACTERISTICS						
Current Gain Bandwidth Product (I_C = 1 Adc, V_{CE} = 10 Vdc, f_{test} = 1 MHz)		f_T	–	13	–	MHz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f_{test} = 1 MHz)		C_{ob}	–	300	500	pF
Input Capacitance (V_{EB} = 8.0)		C_{ib}	–	7000	9000	pF
SWITCHING CHARACTERISTICS: Resistive Load (D.C. = 10%, Pulse Width = 70 μs)						
Turn−On Time	(I_C = 10 Adc, I_{B1} = I_{B2} = 2 Adc, Vcc = 125 V)	t_{On}	–	540	750	ns
Storage Time		t_s	–	4.75	6	μs
Fall Time		t_f	–	380	500	ns
Turn−Off Time		t_{Off}	–	5.2	6.5	μs
Turn−On Time	(I_C= 20 Adc, I_{B1} = I_{B2} = 4 Adc, Vcc = 125 V)	t_{On}	–	965	1200	ns
Storage Time		t_s	–	2.9	3.5	μs
Fall Time		t_f	–	350	500	ns
Turn−Off Time		t_{Off}	–	3.25	4	μs
SWITCHING CHARACTERISTICS: Inductive Load (V_{clamp}= 300 V , Vcc = 15 V, L = 200 μH)						
Fall Time	(I_C = 10 Adc, I_{B1} = I_{B2} = 2 Adc)	t_{fi}	–	142	250	ns
Storage Time		t_{si}	–	4.75	6	μs
Crossover Time		t_c	–	320	500	ns
Fall Time	(I_C = 20 Adc, I_{B1} = I_{B2} = 4 Adc)	t_{fi}	–	350	500	ns
Storage Time		t_{si}	–	3.0	3.5	μs
Crossover Time		t_c	–	500	750	ns

TYPICAL CHARACTERISTICS

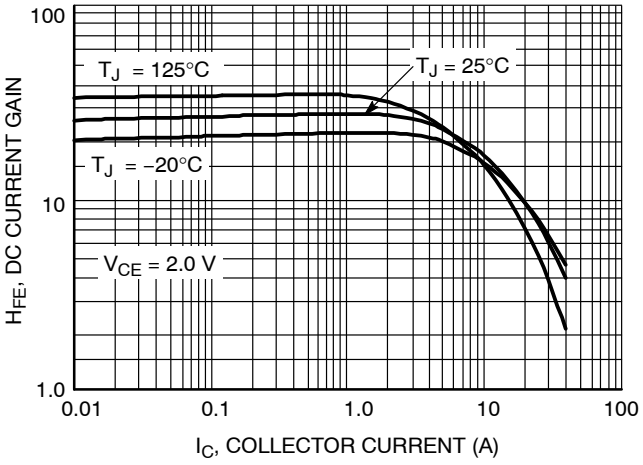


Figure 1. DC Current Gain, V_{CE} = 2.0 V

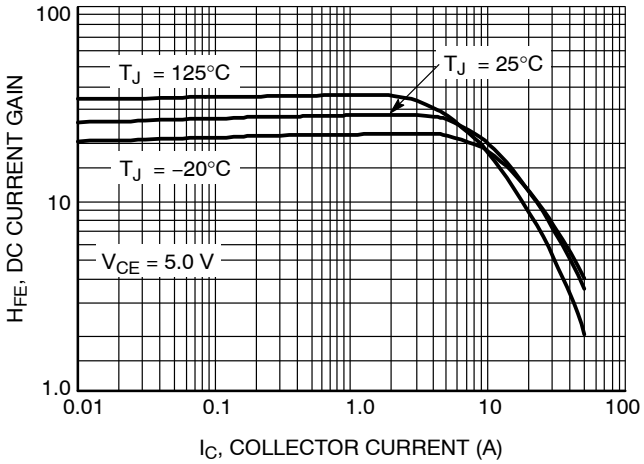


Figure 2. DC Current Gain, V_{CE} = 5.0 V

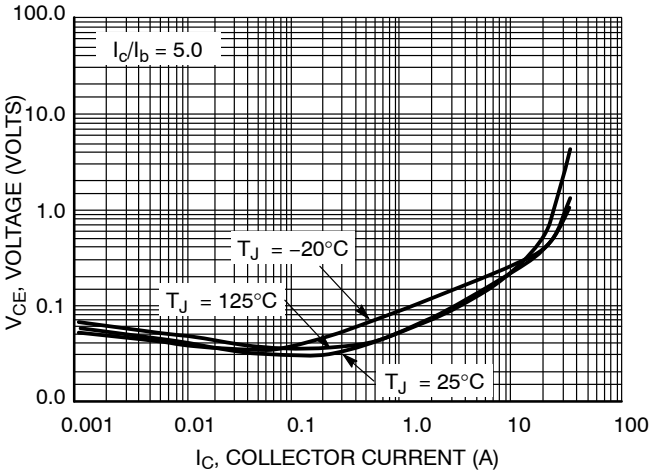


Figure 3. Typical Collector−Emitter Saturation Voltage, I_C/I_B = 5.0

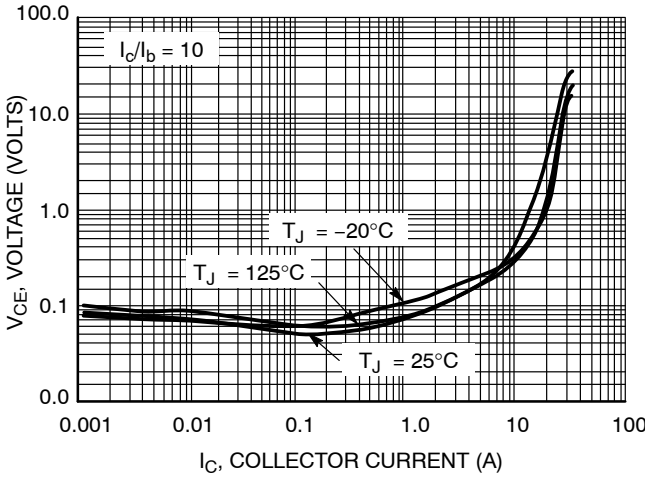


Figure 4. Typical Collector−Emitter Saturation Voltage, I_C/I_B = 10

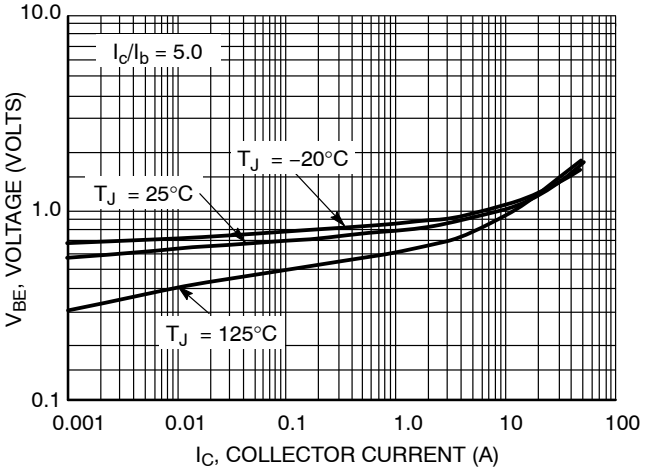


Figure 5. Typical Base−Emitter Saturation Voltage, I_C/I_B = 5.0

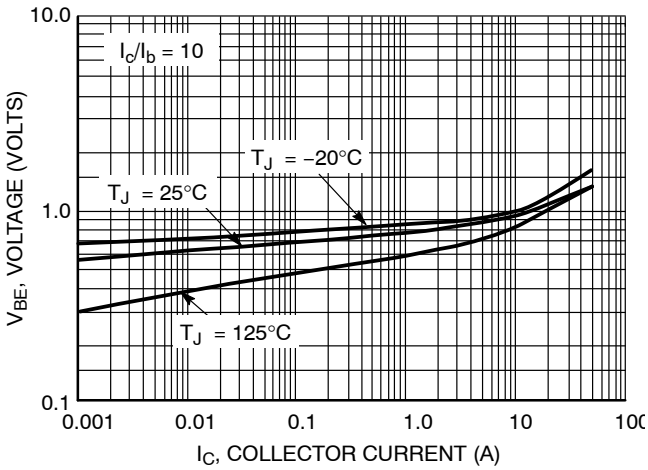


Figure 6. Typical Base−Emitter Saturation Voltage, I_C/I_B = 10

TYPICAL CHARACTERISTICS

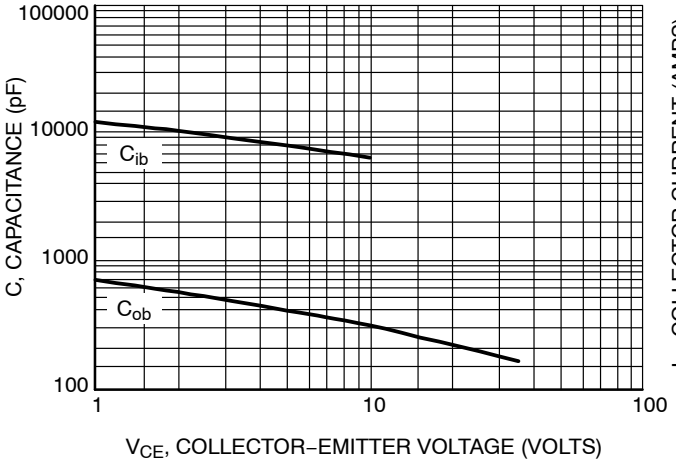


Figure 7. Typical Capacitance

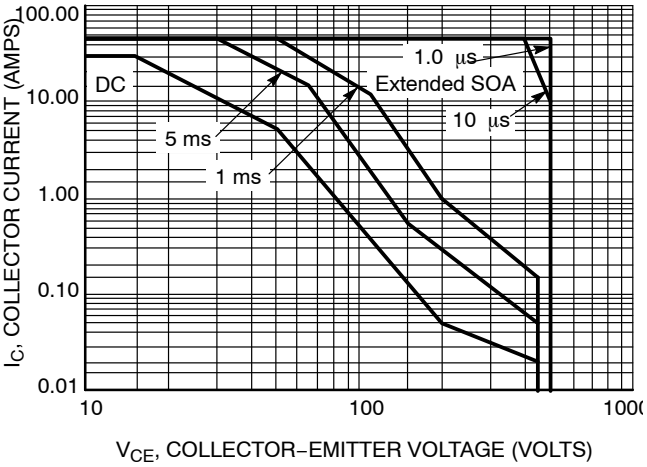


Figure 8. Forward Bias Safe Operating Area

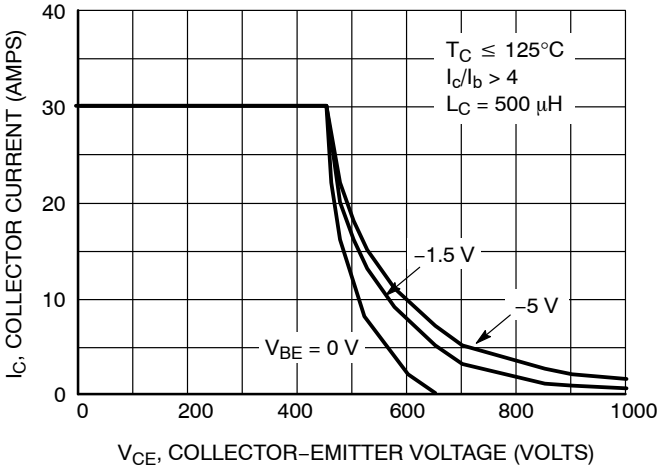
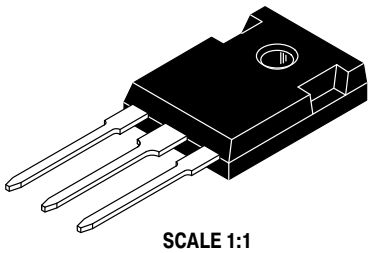


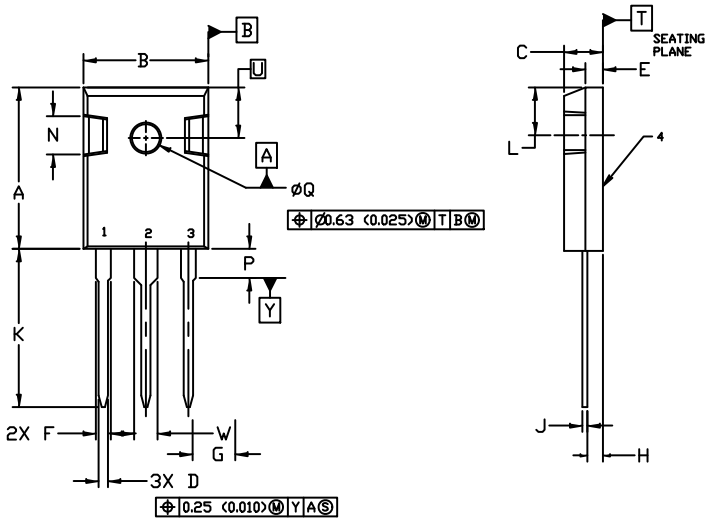
Figure 9. Reverse Bias Safe Operating Area



SCALE 1:1

TO−247
CASE 340L
ISSUE G

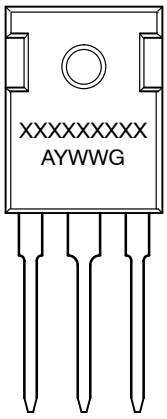
DATE 06 OCT 2021



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER

	MILLIMETERS		INCHES	
DIM	MIN.	MAX.	MIN.	MAX.
A	20.32	21.08	0.800	0.830
B	15.75	16.26	0.620	0.640
C	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
E	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
H	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
P	----	4.50	----	0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123

GENERIC MARKING DIAGRAM*



STYLE 1:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 2:
PIN 1. ANODE
2. CATHODE (S)
3. ANODE 2
4. CATHODES (S)

STYLE 3:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 5:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 6:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. MAIN TERMINAL 2

XXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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